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Substitute for form 1449A/PTO INFORMATION DISCLOSURE STATEMENT BY APPLICANT (use as many sheets as necessary)				<i>Complete if Known</i>	
				Application Number	
				Filing Date	
				First Named Inventor	
				Group Art Unit	
				Examiner Name	
Sheet	1	of	2	Attorney Docket Number	SC11852HP

[illegible][illegible]

Examiner Signature	<i>Luan Thai</i>	Date Considered	<i>01/11/03</i>
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EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609. Draw line through citation, if not in conformance and not considered. Include copy of this form with next communication to applicant.

¹ Unique citation designation number. ² See Kinds of U.S. Patent Documents. ³ Enter Office that issued the document, by the two-letter code (WIPO Standard ST.3). ⁴ For Japanese patent documents, the indication of the year of the reign of the Emperor must precede the serial number of the patent document. ⁵ Kind of document by the appropriate symbols as indicated on the document under WIPO Standard ST. 16 if possible. ⁶ Applicant is to place a check mark here if English Language Translation is attached.

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		Application Number	
		Filing Date	
		First Named Inventor	MAN HON CHENG
		Group Art Unit	
		Examiner Name	
Sheet 2	of 2	Attorney Docket Number	SC11852HP

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OTHER PRIOR ART - NON PATENT LITERATURE DOCUMENTS			
Examiner Initials*	Cite No. ¹	Include name of the author (in CAPITAL LETTERS), title of the article (when appropriate), title of the item (book, magazine, journal, serial, symposium, catalog, etc.), date, page(s), volume-issue number(s), publisher, city and/or country where published.	T ²
	3	NATIONAL SEMICONDUCTOR CORPORATION, Semiconductor Packaging Assembly Technology, August 1999	
	4	NATIONAL SEMICONDUCTOR CORPORATION, Plastic Package Moisture-Induced Cracking, August 1999	
	5	RUIHUA HAN, LINHUO SHI, AND MAHESH GUPTA, Three-Dimensional Simulation of Microchip Encapsulation Process, Department of Mechanical Engineering-Engineering Mechanics, Michigan Technological University, Houghton, Michigan 49931	

Examiner Signature	Luan Thai	Date Considered	1/03
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